Infineon Technologies - MB91F523FSCPMC-GSE1 Datasheet

Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	FR81S
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	CANbus, CSIO, I²C, LINbus, SPI, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	76
Program Memory Size	448KB (448K x 8)
Program Memory Type	FLASH
EEPROM Size	64K x 8
RAM Size	56K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 37x12b; D/A 2x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/mb91f523fscpmc-gse1

Product lineup comparison 144 pins

	MB91F522K	MB91F523K	MB91F524K	MB91F525K	MB91F526K
System Clock	On chip PLL Clock multiple method				
Minimum instruction execution time	12.5ns (80MHz)				
Flash Capacity (Program)	(256+64)KB	(384+64)KB	(512+64)KB	(768+64)KB	(1024+64)KB
Flash Capacity (Data)	64KB				
RAM Capacity	(48+8)KB		(64+8)KB	(96+8)KB	(128+8)KB
External BUS I/F (22address/16data/4cs)	Yes				
DMA Transfer	16ch				
16-bit Base Timer	2ch				
Free-run Timer	16bit×3ch, 32bit×3ch				
Input capture	16bit×4ch, 32bit×6ch				
Output Compare	16bit×6ch, 32bit×6ch				
16-bit Reload Timer	8ch				
PPG	16bit×44ch				
Up/down Counter	2ch				
Clock Supervisor	Yes				
External Interrupt	8ch×2units				
A/D converter	12bit×32ch (1unit), 12bit×16ch (1unit)				
D/A converter (8bit)	2ch				
Multi-Function Serial Interface	12ch*1				
CAN	64msg×2ch/128msg×1ch				
Hardware Watchdog Timer	Yes				
CRC Formation	Yes				
Low-voltage detection reset	Yes				
Flash Security	Yes				
ECC Flash/WorkFlash	Yes				
ECC RAM	Yes				
Memory Protection Function (MPU)	Yes				
Floating point arithmetic (FPU)	Yes				
Real Time Clock (RTC)	Yes				
General-purpose port (#GPIOs)	120 ports				
SSCG	Yes				
Sub clock	Yes				
CR oscillator	Yes				
NMI request function	Yes				
OCD (On Chip Debug)	Yes				
TPU (Timing Protection Unit)	Yes				
Key code register	Yes				
Waveform generator	6ch				
Operation guaranteed temperature (T_A)	-40°C to +125°C				
Power supply	2.7V to 5.5V *2				
Package	LQS144, LQN144				

*1: Only channel 3 and channel 4 support the I^2C (fast mode/standard mode).
Only channel 5, channel 6, channel 7, channel 8, channel 10 and channel 11 support the I^2C (standard mode).

*2: The initial detection voltage of the external low voltage detection is 2.8V±8% (2.576V to 3.024V). This LVD setting and internal LVD cannot be used to reliably generate a reset before voltage dips below minimum guaranteed operation voltage, as these detection levels are below the minimum guaranteed MCU operation voltage. Below the minimum guaranteed MCU operation voltage, MCU operations are not guaranteed with the exception of LVD.

3. Pin Description

Pin no.						Pin Name	Polarity	I/O circuit types*8	Function*9
64	80	100	120	144	176				
-	-	-	-	2	2	P015	-	A	General-purpose I/O port
						D29	-		External bus data bit29 I/O (0)
						TRG0_0	-		PPG trigger 0 input (0)
-	-	-	-	3	3	P016	-	A	General-purpose I/O port
						D30	-		External bus data bit30 I/O (0)
						TRG1_0	-		PPG trigger 1 input (0)
-	-	-	-	-	4	P170	-	A	General-purpose I/O port
						PPG36_1	-		PPG ch.36 output (1)
-	-	-	-	4	5	P017	-	A	General-purpose I/O port
						D31	-		External bus data bit31 I/O (0)
						TRG2_0	-		PPG trigger 2 input (0)
-	-	-	-	-	6	P171	-	A	General-purpose I/O port
						PPG37_1	-		PPG ch.37 output (1)
2 *1	2 *1	2 *1	2 *1	5	7	P020	-	F	General-purpose I/O port
						ASX *2, *3, *4, *5	-		External bus/Address strobe output
						SIN3_1	-		Multi-function serial ch.3 serial data input (1)
						TRG3_0	-		PPG trigger 3 input (0)
						TIN0_2	-		Reload timer ch.0 event input (2)
						RTO5_1	-		Waveform generator ch.5 output pin (1)
-	-	-	3 *1	6	8	P021	-	A	General-purpose I/O port
						CS0X *5	-		External bus chip select 0 output
						SOT3_1	-		Multi-function serial ch.3 serial data output (1)
						TRG6_1	-		PPG trigger 6 input (1)
						TRG4_0	-		PPG trigger 4 input (0)
-	-	-	4 *1	7	9	P022	-	F	General-purpose I/O port
						CS1X *5	-		External bus chip select 1 output
						SCK3_1	-		Multi-function serial ch.3 clock I/O (1)
						TRG7_1	-		PPG trigger 7 input (1)
						TRG5_0	-		PPG trigger 5 input (0)
-	-	-	5 *1	8	10	P023	-	A	General-purpose I/O port
						RDX *5	-		External bus/Read strobe output
						SCS3_1	-		Serial chip select 3 output (1)
						PPG32_0	-		PPG ch.32 output (0)
						TIN0_0	-		Reload timer ch.0 event input (0)

■ Storage of Semiconductor Devices

Because plastic chip packages are formed from plastic resins, exposure to natural environmental conditions will cause absorption of moisture. During mounting, the application of heat to a package that has absorbed moisture can cause surfaces to peel, reducing moisture resistance and causing packages to crack. To prevent, do the following:

(1) Avoid exposure to rapid temperature changes, which cause moisture to condense inside the product. Store products in locations where temperature changes are slight.

(2) Use dry boxes for product storage. Products should be stored below 70% relative humidity, and at temperatures between 5°C and 30°C.
When you open Dry Package that recommends humidity 40% to 70% relative humidity.

(3) When necessary, Cypress packages semiconductor devices in highly moisture-resistant aluminum laminate bags, with a silica gel desiccant. Devices should be sealed in their aluminum laminate bags for storage.

(4) Avoid storing packages where they are exposed to corrosive gases or high levels of dust.

■ Baking

Packages that have absorbed moisture may be de-moisturized by baking (heat drying). Follow the Cypress recommended conditions for baking.

Condition: 125°C/24 h

■ Static Electricity

Because semiconductor devices are particularly susceptible to damage by static electricity, you must take the following precautions:

(1) Maintain relative humidity in the working environment between 40% and 70%. Use of an apparatus for ion generation may be needed to remove electricity.

(2) Electrically ground all conveyors, solder vessels, soldering irons and peripheral equipment.

(3) Eliminate static body electricity by the use of rings or bracelets connected to ground through high resistance (on the level of 1 MΩ).
Wearing of conductive clothing and shoes, use of conductive floor mats and other measures to minimize shock loads is recommended.

(4) Ground all fixtures and instruments, or protect with anti-static measures.

(5) Avoid the use of styrofoam or other highly static-prone materials for storage of completed board assemblies.

3. Precautions for Use Environment

Reliability of semiconductor devices depends on ambient temperature and other conditions as described above.

For reliable performance, do the following:

(1) Humidity

Prolonged use in high humidity can lead to leakage in devices as well as printed circuit boards. If high humidity levels are anticipated, consider anti-humidity processing.

(2) Discharge of Static Electricity

When high-voltage charges exist close to semiconductor devices, discharges can cause abnormal operation. In such cases, use anti-static measures or processing to prevent discharges.

(3) Corrosive Gases, Dust, or Oil

Exposure to corrosive gases or contact with dust or oil may lead to chemical reactions that will adversely affect the device. If you use devices in such conditions, consider ways to prevent such exposure or to protect the devices.

(4) Radiation, Including Cosmic Radiation

Most devices are not designed for environments involving exposure to radiation or cosmic radiation. Users should provide shielding as appropriate.

Address	Address offset value / Register name				Block
	+0	+1	+2	+3	
000120_H	OCCP6 [R/W] W 00000000 00000000 00000000 00000000				Output Compare 6,7 32-bit OCU
000124_H	OCCP7 [R/W] W 00000000 00000000 00000000 00000000				
000128_H	—	—	OCSH67 [R/W] B,H,W ---0--00	OCSL67 [R/W] B,H,W 0000--00	
$00012C_H$	OCCP8 [R/W] W 00000000 00000000 00000000 00000000				Output Compare 8,9 32-bit OCU
000130_H	OCCP9 [R/W] W 00000000 00000000 00000000 00000000				
000134_H	—	—	OCSH89 [R/W] B,H,W ---0--00	OCSL89 [R/W] B,H,W 0000--00	
000138_H to $0001B4_H$	—	—	—	—	Reserved
$0001B8_H$	EPFR64 [R/W] B,H,W -----00-	EPFR65 [R/W] B,H,W 0000-000	EPFR66 [R/W] B,H,W --000000	EPFR67 [R/W] B,H,W ----0000	Extended port function register
$0001BC_H$	EPFR68 [R/W] B,H,W ----0000	EPFR69 [R/W] B,H,W ----0000	EPFR70 [R/W] B,H,W ---00000	EPFR71 [R/W] B,H,W -0-0-0-0	
$0001C0_H$	EPFR72 [R/W] B,H,W 000000-0	EPFR73 [R/W] B,H,W 00000000	EPFR74 [R/W] B,H,W 00000000	EPFR75 [R/W] B,H,W 00000000	
$0001C4_H$	EPFR76 [R/W] B,H,W 00000000	EPFR77 [R/W] B,H,W --000000	EPFR78 [R/W] B,H,W ------00	EPFR79 [R/W] B,H,W 00000000	
$0001C8_H$	EPFR80 [R/W] B,H,W ---00000	EPFR81 [R/W] B,H,W 00000000	EPFR82 [R/W] B,H,W 00000000	EPFR83 [R/W] B,H,W -0000000	
$0001CC_H$	EPFR84 [R/W] B,H,W 00000000	EPFR85 [R/W] B,H,W --000000	EPFR86 [R/W] B,H,W ---00000	EPFR87 [R/W] B,H,W ------00	
$0001D0_H$	EPFR88 [R/W] B,H,W -------0	—	—	—	
$0001D4_H$	—	—	—	—	Reserved
$0001D8_H$	TMRLRA4 [R/W] H XXXXXXXX XXXXXXXX		TMR4 [R] H XXXXXXXX XXXXXXXX		Reload Timer 4
$0001DC_H$	TMRLRB4 [R/W] H XXXXXXXX XXXXXXXX		TMCSR4 [R/W] B, H,W 00000000 0-000000		
$0001E0_H$ to $0001EC_H$	—	—	—	—	Reserved
$0001F0_H$	TMRLRA5 [R/W] H XXXXXXXX XXXXXXXX		TMR5 [R] H XXXXXXXX XXXXXXXX		Reload Timer 5
$0001F4_H$	TMRLRB5 [R/W] H XXXXXXXX XXXXXXXX		TMCSR5 [R/W] B, H,W 00000000 0-000000		

Address	Address offset value / Register name				Block
	+0	+1	+2	+3	
$000F70_H$	RCRH0 [W] H,W XXXXXXXX	RCRL0 [W] B,H,W XXXXXXXX	UDCRH0 [R] H,W 00000000	UDCRL0 [R] B,H,W 00000000	Up/Down Counter 0
$000F74_H$	CCR0 [R/W] B,H 00000000 -0001000		—	CSR0 [R/W] B 00000000	
$000F78_H$ to $000F7C_H$	—	—	—	—	Reserved
$000F80_H$	RCRH1 [W] H,W XXXXXXXX	RCRL1 [W] B,H,W XXXXXXXX	UDCRH1 [R] H,W 00000000	UDCRL1 [R] B,H,W 00000000	Up/Down Counter 1
$000F84_H$	CCR1 [R/W] B,H 00000000 -0001000		—	CSR1 [R/W] B 00000000	
$000F88_H$	—	—	MSCH45 [R] B,H,W 00000000	MSCL45 [R/W] B,H,W ------00	Input Capture 4,5 32-bit ICU Cycle and pulse width measurement control 45
$000F8C_H$	—	—	MSCH67 [R] B,H,W 00000000	MSCL67 [R/W] B,H,W ------00	Input Capture 6,7 32-bit ICU Cycle and pulse width measurement control 67
$000F90_H$	OCCP10 [R/W] W 00000000 00000000 00000000 00000000				Output Compare 10,11 32-bit OCU
$000F94_H$	OCCP11 [R/W] W 00000000 00000000 00000000 00000000				
$000F98_H$	—	—	OCSH1011 [R/W] B,H,W ---0--00	OCSL1011 [R/W] B,H,W 0000--00	Output Compare 10,11 32-bit OCU
$000F9C_H$	—	—	—	OCLS1011 [R/W] B,H,W ----0000	OCU1011 Output level control register
$000FA0_H$	CPCLR5 [R/W] W 11111111 11111111 11111111 11111111				Free-run Timer 5 32-bit FRT
$000FA4_H$	TCDT5 [R/W] W 00000000 00000000 00000000 00000000				
$000FA8_H$	TCCSH5 [R/W]B,H,W 0-----00	TCCSL5 [R/W]B,H,W -1-00000	—	—	
$000FAC_H$ to $000FCC_H$	—	—	—	—	Reserved

Address	Address offset value / Register name				Block
	+0	+1	+2	+3	
$001B24_H$	PDUT11 [W] H,W XXXXXXXX XXXXXXXX		PTMR11 [R] H,W 11111111 11111111		PPG11
$001B28_H$	PCN211 [R/W] B,H,W --000000 -----110		PSDR11 [R/W] H,W 00000000 00000000		
$001B2C_H$	PTPC11 [R/W] H,W 00000000 00000000		—	—	
$001B30_H$	PCN12 [R/W] B,H,W 00000000 000000-0		PCSR12 [W] H,W XXXXXXXX XXXXXXXX		PPG12
$001B34_H$	PDUT12 [W] H,W XXXXXXXX XXXXXXXX		PTMR12 [R] H,W 11111111 11111111		
$001B38_H$	PCN212 [R/W] B,H,W --000000 -----110		PSDR12 [R/W] H,W 00000000 00000000		
$001B3C_H$	PTPC12 [R/W] H,W 00000000 00000000		—	—	
$001B40_H$	PCN13 [R/W] B,H,W 00000000 000000-0		PCSR13 [W] H,W XXXXXXXX XXXXXXXX		PPG13
$001B44_H$	PDUT13 [W] H,W XXXXXXXX XXXXXXXX		PTMR13 [R] H,W 11111111 11111111		
$001B48_H$	PCN213 [R/W] B,H,W --000000 -----110		PSDR13 [R/W] H,W 00000000 00000000		
$001B4C_H$	PTPC13 [R/W] H,W 00000000 00000000		—	—	
$001B50_H$	PCN14 [R/W] B,H,W 00000000 000000-0		PCSR14 [W] H,W XXXXXXXX XXXXXXXX		PPG14
$001B54_H$	PDUT14 [W] H,W XXXXXXXX XXXXXXXX		PTMR14 [R] H,W 11111111 11111111		
$001B58_H$	PCN214 [R/W] B,H,W --000000 -----110		PSDR14 [R/W] H,W 00000000 00000000		
$001B5C_H$	PTPC14 [R/W] H,W 00000000 00000000		—	—	
$001B60_H$	PCN15 [R/W] B,H,W 00000000 000000-0		PCSR15 [W] H,W XXXXXXXX XXXXXXXX		PPG15
$001B64_H$	PDUT15 [W] H,W XXXXXXXX XXXXXXXX		PTMR15 [R] H,W 11111111 11111111		
$001B68_H$	PCN215 [R/W] B,H,W --000000 -----110		PSDR15 [R/W] H,W 00000000 00000000		
$001B6C_H$	PTPC15 [R/W] H,W 00000000 00000000		—	—	
$001B70_H$	PCN16 [R/W] B,H,W 00000000 000000-0		PCSR16 [W] H,W XXXXXXXX XXXXXXXX		PPG16
$001B74_H$	PDUT16 [W] H,W XXXXXXXX XXXXXXXX		PTMR16 [R] H,W 11111111 11111111		

Address	Address offset value / Register name				Block
	+0	+1	+2	+3	
$001C24_H$	PDUT27 [W] H,W XXXXXXXX XXXXXXXX		PTMR27 [R] H,W 11111111 11111111		PPG27
$001C28_H$	PCN227 [R/W] B,H,W --000000 -----110		PSDR27 [R/W] H,W 00000000 00000000		
$001C2C_H$	PTPC27 [R/W] H,W 00000000 00000000		—	—	PPG27
$001C30_H$	PCN28 [R/W] B,H,W 00000000 000000-0		PCSR28 [W] H,W XXXXXXXX XXXXXXXX		PPG28
$001C34_H$	PDUT28 [W] H,W XXXXXXXX XXXXXXXX		PTMR28 [R] H,W 11111111 11111111		
$001C38_H$	PCN228 [R/W] B,H,W --000000 -----110		PSDR28 [R/W] H,W 00000000 00000000		
$001C3C_H$	PTPC28 [R/W] H,W 00000000 00000000		—	—	
$001C40_H$	PCN29 [R/W] B,H,W 00000000 000000-0		PCSR29 [W] H,W XXXXXXXX XXXXXXXX		PPG29
$001C44_H$	PDUT29 [W] H,W XXXXXXXX XXXXXXXX		PTMR29 [R] H,W 11111111 11111111		
$001C48_H$	PCN229 [R/W] B,H,W --000000 -----110		PSDR29 [R/W] H,W 00000000 00000000		
$001C4C_H$	PTPC29 [R/W] H,W 00000000 00000000		—	—	
$001C50_H$	PCN30 [R/W] B,H,W 00000000 000000-0		PCSR30 [W] H,W XXXXXXXX XXXXXXXX		PPG30
$001C54_H$	PDUT30 [W] H,W XXXXXXXX XXXXXXXX		PTMR30 [R] H,W 11111111 11111111		
$001C58_H$	PCN230 [R/W] B,H,W --000000 -----110		PSDR30 [R/W] H,W 00000000 00000000		
$001C5C_H$	PTPC30 [R/W] H,W 00000000 00000000		—	—	
$001C60_H$	PCN31 [R/W] B,H,W 00000000 000000-0		PCSR31 [W] H,W XXXXXXXX XXXXXXXX		PPG31
$001C64_H$	PDUT31 [W] H,W XXXXXXXX XXXXXXXX		PTMR31 [R] H,W 11111111 11111111		
$001C68_H$	PCN231 [R/W] B,H,W --000000 -----110		PSDR31 [R/W] H,W 00000000 00000000		
$001C6C_H$	PTPC31 [R/W] H,W 00000000 00000000		—	—	
$001C70_H$	PCN32 [R/W] B,H,W 00000000 000000-0		PCSR32 [W] H,W XXXXXXXX XXXXXXXX		PPG32
$001C74_H$	PDUT32 [W] H,W XXXXXXXX XXXXXXXX		PTMR32 [R] H,W 11111111 11111111		

Interrupt factor	Interrupt number		Interrupt level	Offset	Default address for TBR	RN
	Decimal	Hexa decimal				
Clock calibration unit (sub oscillation) Multi-function serial interface ch.9 (reception completed) Multi-function serial interface ch.9 (status)	47	2F	ICR31	340_H	$000FFF40_H$	31*1,*4
A/D converter 0/1/7/10/11/14/15/16/17/22/27/28/31	48	30	ICR32	$33C_H$	$000FFF3C_H$	32
Clock calibration unit (CR oscillation) Multi-function serial interface ch.9 (transmission completed) 16-bit OCU 0 (match) / 16-bit OCU 1 (match)	49	31	ICR33	338_H	$000FFF38_H$	33
32-bit Free-run timer 4 16-bit OCU 2 (match) / 16-bit OCU 3 (match)	50	32	ICR34	334_H	$000FFF34_H$	34*5
16-bit OCU 4 (match) / 16-bit OCU 5 (match)	51	33	ICR35	330_H	$000FFF30_H$	35
32-bit ICU6 (fetching/measurement) Multi-function serial interface ch.10 (reception completed) Multi-function serial interface ch.10 (status)	52	34	ICR36	$32C_H$	$000FFF2C_H$	36*1
Multi-function serial interface ch.10 (transmission completed)	53	35	ICR37	328_H	$000FFF28_H$	37
32-bit ICU8 (fetching/measurement) Multi-function serial interface ch.11 (reception completed) Multi-function serial interface ch.11 (status)	54	36	ICR38	324_H	$000FFF24_H$	38*1
32-bit ICU9 (fetching/measurement) WG dead timer underflow 0 / 1/ 2 WG dead timer reload 0 / 1/ 2 WG DTTI 0	55	37	ICR39	320_H	$000FFF20_H$	39
32-bit ICU4 (fetching/measurement) Multi-function serial interface ch.11 (transmission completed)	56	38	ICR40	$31C_H$	$000FFF1C_H$	40
32-bit ICU5 (fetching/measurement) A/D converter 32/34/35/37/38/40/41/42/43/44/45/46/47	57	39	ICR41	318_H	$000FFF18_H$	41
32-bit OCU7/11 (match)	58	3A	ICR42	314_H	$000FFF14_H$	42
32-bit OCU8/9 (match)	59	3B	ICR43	310_H	$000FFF10_H$	43
-	60	3C	ICR44	$30C_H$	$000FFF0C_H$	-*6
- -	61	3D	ICR45	308_H	$000FFF08_H$	-
DMAC0/1/2/3/4/5/6/7/8/9/10/11/12/13/14/15	62	3E	ICR46	304_H	$000FFF04_H$	-
Delay interrupt	63	3F	ICR47	300_H	$000FFF00_H$	-
System reserved (Used for REALOS™*8)	64	40	-	$2FC_H$	$000FFEFC_H$	-
System reserved (Used for REALOS)	65	41	-	$2F8_H$	$000FFEF8_H$	-

Interrupt factor	Interrupt number		Interrupt level	Offset	Default address for TBR	RN
	Decimal	Hexa decimal				
Used with the INT instruction	66 | 255	42 | FF	-	$2F4_H$ | 000_H	$000FFEF4_H$ | $000FFC00_H$	-

Note: It does not support a DMA transfer request caused by an interrupt generated from a peripheral to which no RN (Resource Number) is assigned.

*1: It does not support a DMA transfer by the status of the multi-function serial interface and I^2C reception.

*2: Reload timer ch.4 to ch.7 do not support a DMA transfer by the interrupt.

*3: PPG ch.24 to ch.47 do not support a DMA transfer by the interrupt.

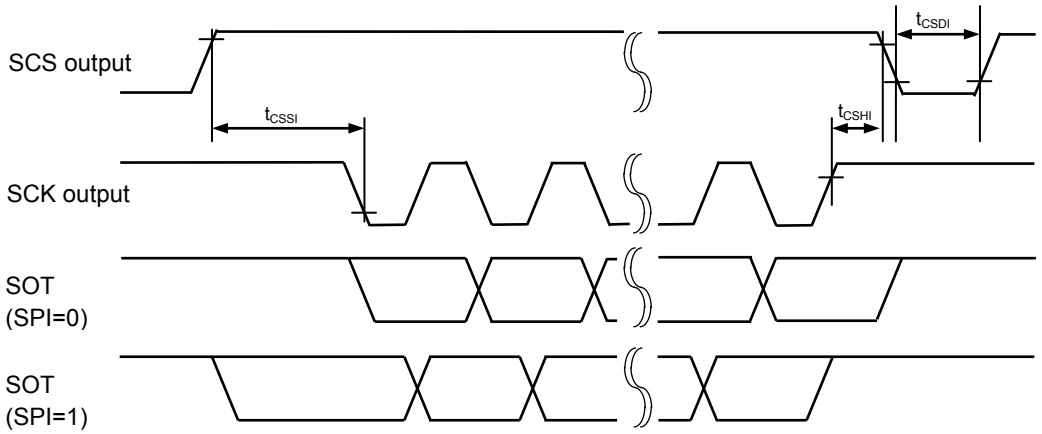
*4: The clock calibration unit does not support a DMA transfer by the interrupt.

*5: 32-bit Free-run timer ch.3, ch.4 and ch.5 do not support a DMA transfer by the interrupt.

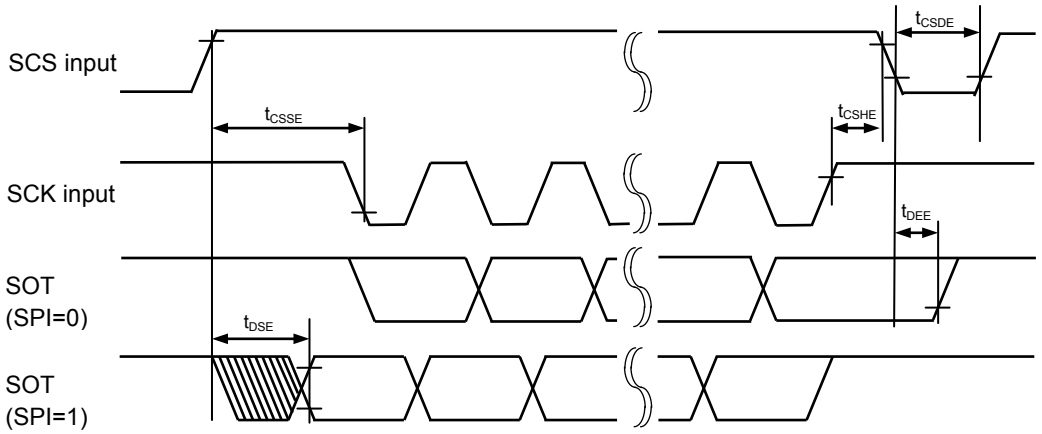
*6: There is no resource corresponding to the interrupt level.

*7: It does not support a DMA transfer by the external low-voltage detection interrupt.

*8: REALOS is a trademark of Cypress.



When Serial chip select is used , Serial clock output mark level "H",
Serial chip select Inactive level "L"
Internal shift clock mode



When Serial chip select is used , Serial clock output mark level "H",
Serial chip select Inactive level "L"
External shift clock mode

Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Min	Max		
SCS↑→SCK↑ setup time	t_{CSSE}	SCK1 to SCK11 SCS1 to SCS3, SCS40 to SCS43, SCS50 to SCS53, SCS60 to SCS63, SCS70 to SCS73, SCS8 to SCS11	-	$3t_{CPP}$+30	-	ns	External shift clock mode output pin: C_L=50pF
SCK↓→SCS↓ hold time	t_{CSHE}			+0	-	ns	
SCS deselect time	t_{CSDE}	SCS1 to SCS3, SCS40 to SCS43, SCS50 to SCS53, SCS60 to SCS63, SCS70 to SCS73, SCS8 to SCS11		$3t_{CPP}$+30	-	ns	
SCS↑→SOT delay time	t_{DSE}	SCS1 , SCS2, SCS50~SCS53, SCS60~SCS63, SCS70~SCS73, SCS8~SCS11 SOT1 , SOT2, SOT5~SOT11		-	40	ns	
		SCS3 , SCS40~SCS43 SOT3 ,SOT4		-	300	ns	
SCS↓→SOT delay time	t_{DEE}	SCS1 to SCS3, SCS40 to SCS43, SCS50 to SCS53, SCS60 to SCS63, SCS70 to SCS73, SCS8 to SCS11 SOT1 to SOT11	-	+0	-	ns	External shift clock mode output pin: C_L=50pF
SCK↑→SCS↑ clock switch time	t_{SCC}	SCK1 , SCK2, SCK5 to SCK11 SCS1 , SCS2, SCS50 to SCS53, SCS60 to SCS63, SCS70 to SCS73, SCS8 to SCS11	-	$3t_{CPP}$-10	$3t_{CPP}$+50	ns	Internal shift clock mode Round operation output pin: C_L=50pF
		SCK3 , SCK4 SCS3 , SCS40 to SCS43		$3t_{CPP}$-300	$3t_{CPP}$+50		

*1: t_{CSSU} =SCSTR:CSSU7-0×Serial chip select timing operating clock
*2: t_{CSHD}=SCSTR:CSHD7-0×Serial chip select timing operating clock
*3: t_{CSDS}=SCSTR:CSDS15-0×Serial chip select timing operating clock
Regardless of the deselect time setting, once after the serial chip select pin becomes inactive, it will take at least five peripheral bus clock cycles to be active again

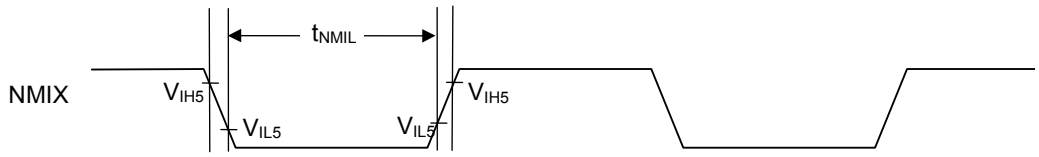
Please see the hardware manual for details of above-mentioned *1,*2, and *3.

(7) NMI input timing

(T_A: -40°C to +125°C, V_{CC}= AV_{CC}=5.0V ± 10%/V_{CC}=AV_{CC}=3.3V±0.3V, V_{SS}=AV_{SS}=0.0V)

Parameter	Symbol	Pin name	Conditions	Value		Unit	Remarks
				Min	Max		
Input pulse width	t_{NMIL}	NMIX	–	$4t_{CPP}$	–	ns	

・NMIX input timing



(8) Low voltage detection (External low-voltage detection)

(T_A: -40°C to +125°C, V_{SS}=AV_{SS}=0.0V)

Parameter	Symbol	Pin name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
Power supply voltage range	V_{DP5}	VCC	-	2.7	-	5.5	V	
Detection voltage*3	V_{DL}		*1	-8%	LVD5F_SEL [3:0]	+8%	V	LVD5F_SEL[3:0] are programmable. Refer to the hardware manual.
Hysteresis width	V_{HYS}		-	-	0.1	-	V	When power-supply voltage rises
Low voltage detection time	Td	-		-	-	30	µs	
Power supply voltage regulation	-	VCC	-	-2	-	2	V/ms	*2

*1: If the fluctuation of the power supply is faster than the low voltage detection time, there is a possibility to generate or release after the power supply voltage has exceeded the detection voltage range.

*2: Please suppress the change of the power supply within the range of the power-supply voltage regulation to do a low voltage detection by detecting voltage (V_{DL}).

*3: The initial detection voltage of the external low voltage detection is 2.8V±8% (2.576V to 3.024V).
This LVD setting cannot be used to reliably generate a reset before voltage dips below minimum guaranteed MCU operation voltage, as this detection level is below the minimum guaranteed MCU operation voltage (2.7V).
Below the minimum guaranteed MCU operation voltage, MCU operations are not guaranteed with the exception of LVD.

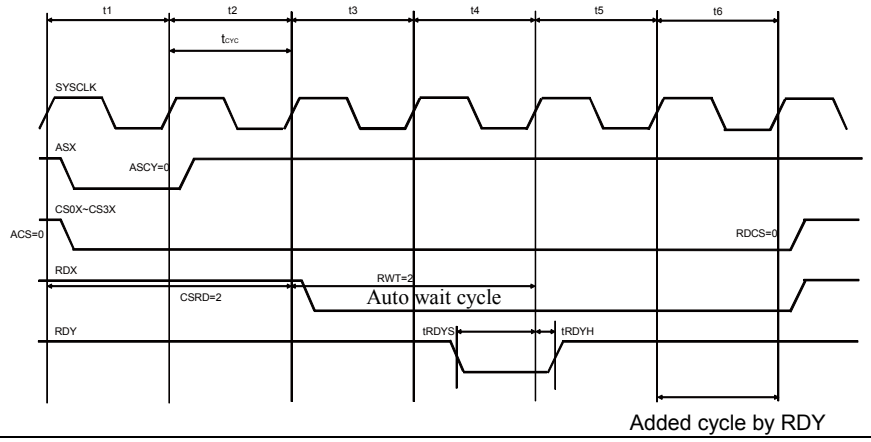
(12) External bus I/F (ready) Timing

(T_A: -40°C to +105°C, V_{CC}=AV_{CC}=5.0V ± 10%/V_{CC}= AV_{CC}=3.3V±0.3V, V_{SS}=AV_{SS}=0.0V)

(external load capacitance 50pF)

Parameter	Symbol	Pin name	Value		Unit	Remarks
			Min	Max		
Cycle time	t_{CYC}	SYSCLK	50	-	ns	If using RDY, set SYSCLK to 20 MHz or less.
RDY setup time → SYSCLK↑	t_{RDYS}	SYSCLK, RDY	28	-	ns	
SYSCLK↑→ RDY hold time	t_{RDYH}	SYSCLK, RDY	0	-	ns	

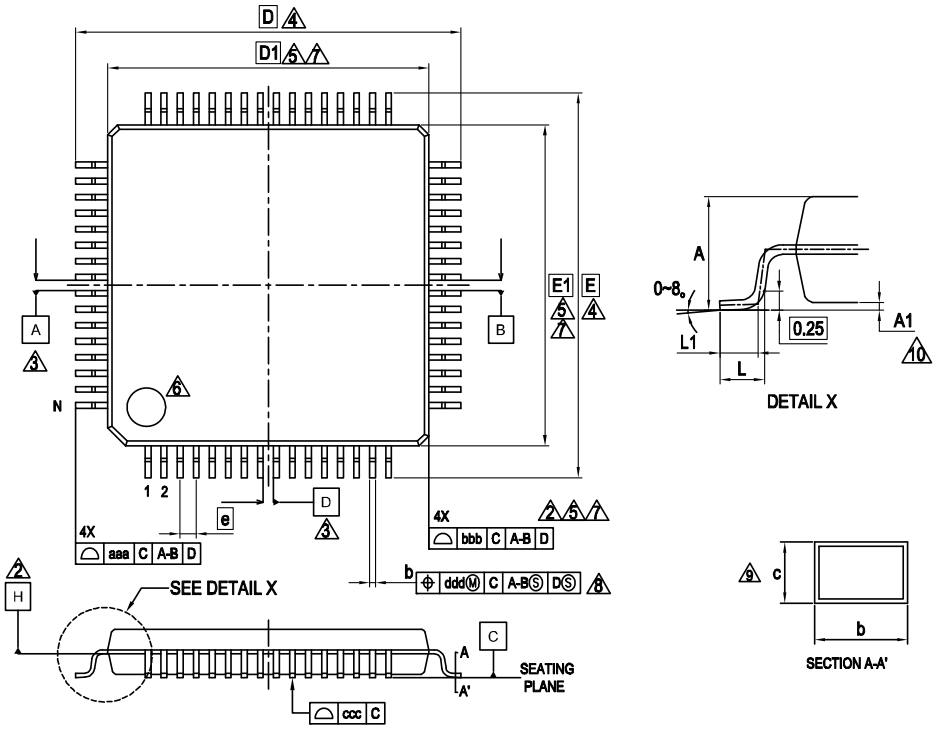
External bus I/F (ready) Timing



Part number	Sub clock	CSV Initial value	LVD Initial value	Package*2
MB91F526FWCPMC	Yes	ON	ON	LQI・100 pin, Plastic
MB91F526FYCPMC			OFF	
MB91F526FJCPMC		OFF	ON	
MB91F526FLCPMC			OFF	
MB91F525FWCPMC		ON	ON	
MB91F525FYCPMC			OFF	
MB91F525FJCPMC		OFF	ON	
MB91F525FLCPMC			OFF	
MB91F524FWCPMC		ON	ON	
MB91F524FYCPMC			OFF	
MB91F524FJCPMC		OFF	ON	
MB91F524FLCPMC			OFF	
MB91F523FWCPMC		ON	ON	
MB91F523FYCPMC			OFF	
MB91F523FJCPMC		OFF	ON	
MB91F523FLCPMC			OFF	
MB91F522FWCPMC		ON	ON	
MB91F522FYCPMC			OFF	
MB91F522FJCPMC		OFF	ON	
MB91F522FLCPMC			OFF	
MB91F526FSCPMC	None	ON	ON	
MB91F526FUCPMC			OFF	
MB91F526FHCPMC		OFF	ON	
MB91F526FKCPMC			OFF	
MB91F525FSCPMC		ON	ON	
MB91F525FUCPMC			OFF	
MB91F525FHCPMC		OFF	ON	
MB91F525FKCPMC			OFF	
MB91F524FSCPMC		ON	ON	
MB91F524FUCPMC			OFF	
MB91F524FHCPMC		OFF	ON	
MB91F524FKCPMC			OFF	
MB91F523FSCPMC		ON	ON	
MB91F523FUCPMC			OFF	
MB91F523FHCPMC		OFF	ON	
MB91F523FKCPMC			OFF	
MB91F522FSCPMC		ON	ON	
MB91F522FUCPMC			OFF	
MB91F522FHCPMC		OFF	ON	
MB91F522FKCPMC			OFF	

17. Package Dimensions

LQD064 , 64 Lead Plastic Low Profile Quad Flat Package



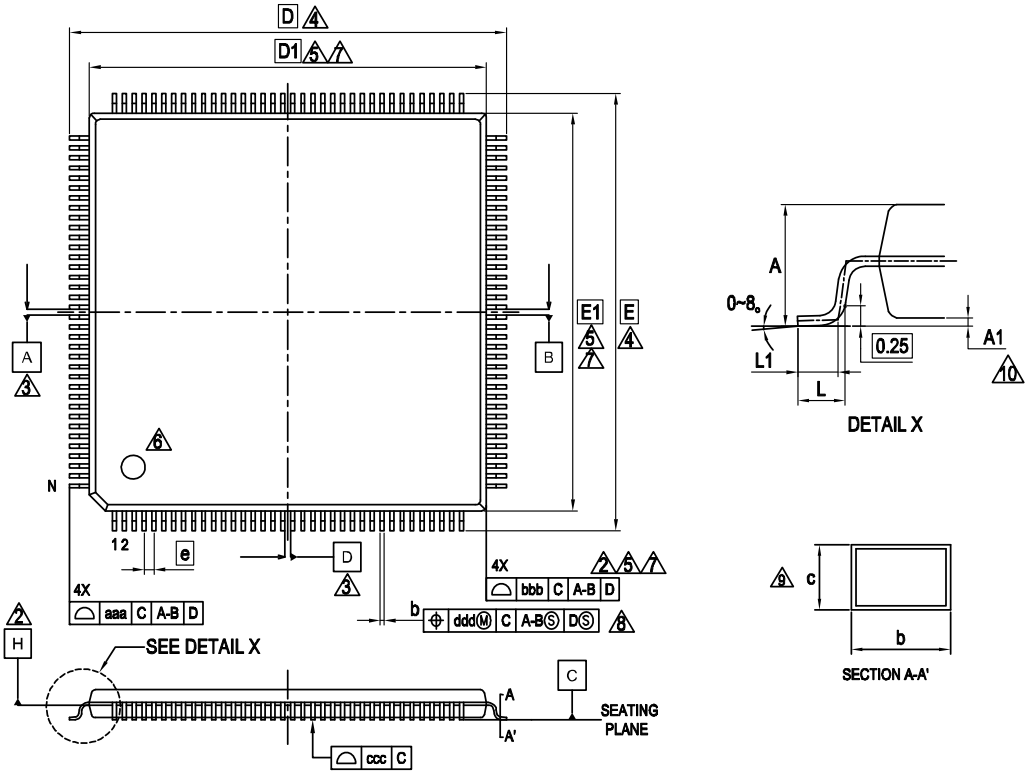
PACKAGE	LQD64		
SYMBOL	MIN.	NOM.	MAX.
A	—	—	1.70
A1	0.00	—	0.20
b	0.15	0.20	0.25
c	0.09	—	0.20
D	12.00 BSC.		
D1	10.00 BSC.		
e	0.50 BSC		
E	12.00 BSC.		
E1	10.00 BSC.		
L	0.45	0.60	0.75
L1	0.30	0.50	0.70
aaa	—	—	0.20
bbb	—	—	0.10
ccc	—	—	0.08
ddd	—	—	0.08
N	64		

NOTES

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (mm)
2. DATUM PLANE H IS LOCATED AT THE BOTTOM OF THE MOLD PARTING LINE COINCIDENT WITH WHERE THE LEAD EXITS THE BODY.
3. DATUMS A-B AND D TO BE DETERMINED AT DATUM PLANE H.
4. TO BE DETERMINED AT SEATING PLANE C.
5. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25mm PRE SIDE. DIMENSIONS D1 AND E1 INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
6. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED.
7. REGARDLESS OF THE RELATIVE SIZE OF THE UPPER AND LOWER BODY SECTIONS. DIMENSIONS D1 AND E1 ARE DETERMINED AT THE LARGEST FEATURE OF THE BODY EXCLUSIVE OF MOLD FLASH AND GATE BURRS. BUT INCLUDING ANY MISMATCH BETWEEN THE UPPER AND LOWER SECTIONS OF THE MOLDER BODY.
8. DIMENSION b DOES NOT INCLUDE DAMBER PROTRUSION. THE DAMBAR PROTRUSION (S) SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED b MAXIMUM BY MORE THAN 0.08mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE LEAD FOOT.
9. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10mm AND 0.25mm FROM THE LEAD TIP.
10. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.

Rev. A

LQS144 , 144 Lead Plastic Low Profile Quad Flat Package



PACKAGE	LQS144		
SYMBOL	MIN.	NOM.	MAX.
A	—	—	1.70
A1	0.06	—	0.26
b	0.17	0.22	0.27
c	0.09	—	0.20
D	22.00 BSC.		
D1	20.00 BSC.		
e	0.50 BSC		
E	22.00 BSC.		
E1	20.00 BSC.		
L	0.45	0.60	0.75
L1	0.30	0.50	0.70
aaa	—	—	0.20
bbb	—	—	0.10
ccc	—	—	0.08
ddd	—	—	0.08
N	144		

NOTES

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (mm)
2. DATUM PLANE H IS LOCATED AT THE BOTTOM OF THE MOLD PARTING LINE COINCIDENT WITH WHERE THE LEAD EXITS THE BODY.
3. DATUMS A-B AND D TO BE DETERMINED AT DATUM PLANE H.
4. TO BE DETERMINED AT SEATING PLANE C.
5. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25mm PRE SIDE. DIMENSIONS D1 AND E1 INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.
6. DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED.
7. REGARDLESS OF THE RELATIVE SIZE OF THE UPPER AND LOWER BODY SECTIONS. DIMENSIONS D1 AND E1 ARE DETERMINED AT THE LARGEST FEATURE OF THE BODY EXCLUSIVE OF MOLD FLASH AND GATE BURRS. BUT INCLUDING ANY MISMATCH BETWEEN THE UPPER AND LOWER SECTIONS OF THE MOLDER BODY.
8. DIMENSION b DOES NOT INCLUDE DAMBER PROTRUSION. THE DAMBAR PROTRUSION (S) SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED b MAXIMUM BY MORE THAN 0.08mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE LEAD FOOT.
9. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10mm AND 0.25mm FROM THE LEAD TIP.
10. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT OF THE PACKAGE BODY.

Rev. A

■ **Workaround**

It is necessary to satisfy the below both conditions of (1) and (2).

(1) Interrupt levels that are used as sources for recovering from the watch mode (power off) are ‘31’, before CPU state changes to the watch mode (power off)

(2) Don’t use NMIX pin as source for recovering from the watch mode (power off)

■ **Fix Status**

Will not be planned

19. Major Changes

Spansion Publication Number: MB91F526L_DS705-00011

Page	Section	Change Results
Revision 1.0		
-	-	Initial release
Revision 2.0		
3	■FEATURES	Corrected the following description. 5V tolerant input: 4 channels ch.6, ch.8, ch.9, ch.11 Automotive input ↓ 5V tolerant input: 4 channels ch.6, ch.8, ch.9, ch.11 CMOS hysteresis input
33 to 36	■I/O CIRCUIT TYPE	Corrected the following description to "Type F, G, I, J, K, M". Schmitt input → CMOS hysteresis input Corrected the following description to "Type D, E". I^2C Schmitt input → I^2C hysteresis input
44 to 49	■BLOCK DIAGRAM	Corrected the following description. ●MB91F522B, MB91F523B, MB91F524B, MB91F525B, MB91F526B ●MB91F522D, MB91F523D, MB91F524D, MB91F525D, MB91F526D ●MB91F522F, MB91F523F, MB91F524F, MB91F525F, MB91F526F ●MB91F522J, MB91F523J, MB91F524J, MB91F525J, MB91F526J ●MB91F522K, MB91F523K, MB91F524K, MB91F525K, MB91F526K ●MB91F522L, MB91F523L, MB91F524L, MB91F525L, MB91F526L
138	■ELECTRICAL CHARACTERISTICS 2. Recommended operating conditions	Added the following description. *1 : When it is used outside recommended operation guarantee range (range of the operation guarantee),contact your sales representative. Moreover, minimum value with an effective external low-voltage detection reset becomes a voltage until generating low-voltage detection reset
139,140	■ELECTRICAL CHARACTERISTICS 3.DC characteristics	Corrected the value of "ICCT5 When using sub clock 32kHz TA=+25°C ". Max 1420µA → Max 2000µA
139	■ELECTRICAL CHARACTERISTICS 3.DC characteristics	Corrected the value of "Power supply voltage range". (TA:-40°C to +105°C,Vcc=AVcc=2.7V to 5.5V,VSS=AVSS=0.0V) ↓ (T_A:-40°C to +105°C,Vcc=AVcc=5.0V±10%/3.3V±0.3V,V_{SS}=AV_{SS}=0.0V)
140,141	■ELECTRICAL CHARACTERISTICS 3.DC characteristics	Corrected the value of "Power supply voltage range". (T_A:-40°C to +125°C,Vcc=AVcc=2.7V to 5.5V,VSS=AVSS=0.0V) ↓ (T_A:-40°C to +125°C,Vcc=AVcc=5.0V±10%/3.3V±0.3V,V_{SS}=AV_{SS}=0.0 V)
141	■ELECTRICAL CHARACTERISTICS 3.DC characteristics	Corrected the value of " Pull-up resistance R_{UP1}". Vcc=3.3V±0.3V Min 49 Max 140 →Min 45 Max 140

Page	Section	Change Results
24	■PIN Description	A List of "Pin Description" modified. (Error) Function*2 General-purpose I/O port External Bus chip select 3 output pin(0) Input capture ch.9 input pin(0) PPG ch.0 output pin(1) Input capture ch.0 input pin(1) Reload timer ch.5 event input pin(1) Waveform generator ch.0 to ch.5 input pin(2) (Correct) Function*9 General-purpose I/O port External Bus chip select 3 output pin Input capture ch.9 input pin(0) PPG ch.0 output pin(1) Input capture ch.0 input pin(1) Reload timer ch.5 event input pin(1) Waveform generator ch.0 to ch.5 input pin(2)

<table>
<tr><th>Page</th><th>Section</th><th>Change Results</th></tr>
<tr><td>184</td><td>11. Electrical Characteristics
AC Characteristics
(4-4) I2C timing</td><td>The following sentence modified as following:

(Error)
<table><tr><th colspan="2">High-speed mode*3</th><th rowspan="2">Unit</th><th rowspan="2">Remarks</th></tr><tr><th>Min</th><th>Max</th></tr></table>
Notes: Only ch.3 and ch.4 are standard mode/high-speed mode correspondence.

*3: A high-speed mode I2C bus device can be used

(Correct)
<table><tr><th colspan="2">Fast mode*3</th><th rowspan="2">Unit</th><th rowspan="2">Remarks</th></tr><tr><th>Min</th><th>Max</th></tr></table>
Notes: Only ch.3 and ch.4 are standard mode/fast mode correspondence.

*3: A fast mode I2C bus device can be used</td></tr>
<tr><td>187</td><td>11. Electrical Characteristics
(8) Low voltage detection (External low-voltage detection)</td><td>The following sentence modified in the Detection voltage as following:

(Error)
<table><tr><th colspan="3">Value</th><th rowspan="2">Unit</th><th rowspan="2">Remarks</th></tr><tr><th>Min</th><th>Typ</th><th>Max</th></tr><tr><td>2.7</td><td>-</td><td>5.5</td><td>V</td><td></td></tr><tr><td>-8%</td><td>2.8</td><td>+8%</td><td>V</td><td>When power-supply voltage falls and detection level is set initially</td></tr></table>
(Correct)
<table><tr><th colspan="3">Value</th><th rowspan="2">Unit</th><th rowspan="2">Remarks</th></tr><tr><th>Min</th><th>Typ</th><th>Max</th></tr><tr><td>2.7</td><td>-</td><td>5.5</td><td>V</td><td></td></tr><tr><td>-8%</td><td>LVD5F_SEL [3:0]</td><td>+8%</td><td>V</td><td>LVD5F_SEL[3:0] are programmable. Refer to the hardware manual.</td></tr></table></td></tr>
<tr><td>188</td><td>11. Electrical Characteristics
(9) Low voltage detection (RAM retention low-voltage detection)</td><td>The following sentence modified as following:

(Error)
(9) Low voltage detection (Internal low-voltage detection)

(Correct)
(9) Low voltage detection (RAM retention low-voltage detection)</td></tr>
</table>